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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	EBI/EMI, I ² C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	88
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/atmel/at91sam7se256-au

3. Signal Description

Table 3-1. Signal Description List

Signal Name	Function	Type	Active Level	Comments
Power				
VDDIN	Voltage Regulator and ADC Power Supply Input	Power		3V to 3.6V
VDDOUT	Voltage Regulator Output	Power		1.85V
VDDFLASH	Flash and USB Power Supply	Power		3V to 3.6V
VDDIO	I/O Lines Power Supply	Power		3V to 3.6V or 1.65V to 1.95V
VDDCORE	Core Power Supply	Power		1.65V to 1.95V
VDDPLL	PLL	Power		1.65V to 1.95V
GND	Ground	Ground		
Clocks, Oscillators and PLLs				
XIN	Main Oscillator Input	Input		
XOUT	Main Oscillator Output	Output		
PLLRC	PLL Filter	Input		
PCK0 - PCK2	Programmable Clock Output	Output		
ICE and JTAG				
TCK	Test Clock	Input		No pull-up resistor
TDI	Test Data In	Input		No pull-up resistor
TDO	Test Data Out	Output		
TMS	Test Mode Select	Input		No pull-up resistor.
JTAGSEL	JTAG Selection	Input		Pull-down resistor ⁽¹⁾
Flash Memory				
ERASE	Flash and NVM Configuration Bits Erase Command	Input	High	Pull-down resistor ⁽¹⁾
Reset/Test				
NRST	Microcontroller Reset	I/O	Low	Open drain with pull-up resistor ⁽¹⁾
TST	Test Mode Select	Input	High	Pull-down resistor ⁽¹⁾
Debug Unit				
DRXD	Debug Receive Data	Input		
DTXD	Debug Transmit Data	Output		
AIC				
IRQ0 - IRQ1	External Interrupt Inputs	Input		
FIQ	Fast Interrupt Input	Input		

4.2 128-lead LQFP Pinout

Table 4-1. Pinout in 128-lead LQFP Package

1	ADVREF	33	PB31	65	TDI	97	SDCK
2	GND	34	PB30	66	TDO	98	PC8
3	AD7	35	PB29	67	PB2	99	PC7
4	AD6	36	PB28	68	PB1	100	PC6
5	AD5	37	PB27	69	PB0	101	PC5
6	AD4	38	PB26	70	GND	102	PC4
7	VDDOUT	39	PB25	71	VDDIO	103	PC3
8	VDDIN	40	PB24	72	VDDCORE	104	PC2
9	PA20/PGMD8/AD3	41	PB23	73	NRST	105	PC1
10	PA19/PGMD7/AD2	42	PB22	74	TST	106	PC0
11	PA18/PGMD6/AD1	43	PB21	75	ERASE	107	PA31
12	PA17/PGMD5/AD0	44	PB20	76	TCK	108	PA30
13	PA16/PGMD4	45	GND	77	TMS	109	PA29
14	PA15/PGMD3	46	VDDIO	78	JTAGSEL	110	PA28
15	PA14/PGMD2	47	VDDCORE	79	PC23	111	PA27/PGMD15
16	PA13/PGMD1	48	PB19	80	PC22	112	PA26/PGMD14
17	PA12/PGMD0	49	PB18	81	PC21	113	PA25/PGMD13
18	PA11/PGMM3	50	PB17	82	PC20	114	PA24/PGMD12
19	PA10/PGMM2	51	PB16	83	PC19	115	PA23/PGMD11
20	PA9/PGMM1	52	PB15	84	PC18	116	PA22/PGMD10
21	VDDIO	53	PB14	85	PC17	117	PA21/PGMD9
22	GND	54	PB13	86	PC16	118	VDDCORE
23	VDDCORE	55	PB12	87	PC15	119	GND
24	PA8/PGMM0	56	PB11	88	PC14	120	VDDIO
25	PA7/PGMINVALID	57	PB10	89	PC13	121	DM
26	PA6/PGMNOE	58	PB9	90	PC12	122	DP
27	PA5/PGMRDY	59	PB8	91	PC11	123	VDDFLASH
28	PA4/PGMNCMD	60	PB7	92	PC10	124	GND
29	PA3	61	PB6	93	PC9	125	XIN/PGMCK
30	PA2/PGMEN2	62	PB5	94	GND	126	XOUT
31	PA1/PGMEN1	63	PB4	95	VDDIO	127	PLLRC
32	PA0/PGMEN0	64	PB3	96	VDDCORE	128	VDDPLL

5. Power Considerations

5.1 Power Supplies

The SAM7SE512/256/32 has six types of power supply pins and integrates a voltage regulator, allowing the device to be supplied with only one voltage. The six power supply pin types are:

- VDDIN pin. It powers the voltage regulator and the ADC; voltage ranges from 3.0V to 3.6V, 3.3V nominal.
- VDDOUT pin. It is the output of the 1.8V voltage regulator.
- VDDIO pin. It powers the I/O lines; two voltage ranges are supported:
 - from 3.0V to 3.6V, 3.3V nominal
 - or from 1.65V to 1.95V, 1.8V nominal.
- VDDFLASH pin. It powers the USB transceivers and a part of the Flash. It is required for the Flash to operate correctly; voltage ranges from 3.0V to 3.6V, 3.3V nominal.
- VDDCORE pins. They power the logic of the device; voltage ranges from 1.65V to 1.95V, 1.8V typical. It can be connected to the VDDOUT pin with decoupling capacitor. VDDCORE is required for the device, including its embedded Flash, to operate correctly.
- VDDPLL pin. It powers the oscillator and the PLL. It can be connected directly to the VDDOUT pin.

In order to decrease current consumption, if the voltage regulator and the ADC are not used, VDDIN, ADVREF, AD4, AD5, AD6 and AD7 should be connected to GND. In this case VDDOUT should be left unconnected.

No separate ground pins are provided for the different power supplies. Only GND pins are provided and should be connected as shortly as possible to the system ground plane.

5.2 Power Consumption

The SAM7SE512/256/32 has a static current of less than 60 μ A on VDDCORE at 25°C, including the RC oscillator, the voltage regulator and the power-on reset when the brownout detector is deactivated. Activating the brownout detector adds 20 μ A static current.

The dynamic power consumption on VDDCORE is less than 80 mA at full speed when running out of the Flash. Under the same conditions, the power consumption on VDDFLASH does not exceed 10 mA.

5.3 Voltage Regulator

The SAM7SE512/256/32 embeds a voltage regulator that is managed by the System Controller.

In Normal Mode, the voltage regulator consumes less than 100 μ A static current and draws 100 mA of output current.

The voltage regulator also has a Low-power Mode. In this mode, it consumes less than 20 μ A static current and draws 1 mA of output current.

Adequate output supply decoupling is mandatory for VDDOUT to reduce ripple and avoid oscillations. The best way to achieve this is to use two capacitors in parallel:

- One external 470 pF (or 1 nF) NPO capacitor should be connected between VDDOUT and GND as close to the chip as possible.

6. /O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are Schmitt trigger inputs. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 k Ω .

To eliminate any risk of spuriously entering the JTAG boundary scan mode due to noise on JTAGSEL, it should be tied externally to GND if boundary scan is not used, or put in place an external low value resistor (such as 1 k Ω).

6.2 Test Pin

The TST pin is used for manufacturing test or fast programming mode of the SAM7SE512/256/32 when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 k Ω to GND.

To eliminate any risk of entering the test mode due to noise on the TST pin, it should be tied to GND if the FFPI is not used, or put in place an external low value resistor (such as 1 k Ω).

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied low.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open-drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the NRST pin as system user reset, and the use of the NRST signal to reset all the components of the system.

An external power-on reset can drive this pin during the start-up instead of using the internal power-on reset circuit.

The NRST pin integrates a permanent pull-up of about 100 k Ω resistor to VDDIO.

This pin has Schmitt trigger input.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 k Ω to GND.

To eliminate any risk of erasing the Flash due to noise on the ERASE pin, it should be tied externally to GND, which prevents erasing the Flash from the application, or put in place an external low value resistor (such as 1 k Ω).

This pin is debounced by the RC oscillator to improve the glitch tolerance. When the pin is tied to high during less than 100 ms, ERASE pin is not taken into account. The pin must be tied high during more than 220 ms to perform the re-initialization of the Flash.

7. Processor and Architecture

7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
 - Runs at up to 55 MHz, providing 0.9 MIPS/MHz (core supplied with 1.8V)
- Two instruction sets
 - ARM® high-performance 32-bit instruction set
 - Thumb® high code density 16-bit instruction set
- Three-stage pipeline architecture
 - Instruction Fetch (F)
 - Instruction Decode (D)
 - Execute (E)

7.2 Debug and Test Features

- EmbeddedICE™ (Integrated embedded in-circuit emulator)
 - Two watchpoint units
 - Test access port accessible through a JTAG protocol
 - Debug communication channel
- Debug Unit
 - Two-pin UART
 - Debug communication channel interrupt handling
 - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

7.3 Memory Controller

- Programmable Bus Arbiter
 - Handles requests from the ARM7TDMI and the Peripheral DMA Controller
- Address decoder provides selection signals for
 - Four internal 1 Mbyte memory areas
 - One 256-Mbyte embedded peripheral area
 - Eight external 256-Mbyte memory areas
- Abort Status Registers
 - Source, Type and all parameters of the access leading to an abort are saved
 - Facilitates debug by detection of bad pointers
- Misalignment Detector
 - Alignment checking of all data accesses
 - Abort generation in case of misalignment
- Remap Command
 - Remaps the SRAM in place of the embedded non-volatile memory
 - Allows handling of dynamic exception vectors
- 16-area Memory Protection Unit (Internal Memory and peripheral protection only)

- Individually programmable size between 1K Byte and 1M Byte
- Individually programmable protection against write and/or user access
- Peripheral protection against write and/or user access
- Embedded Flash Controller
 - Embedded Flash interface, up to three programmable wait states
 - Prefetch buffer, buffering and anticipating the 16-bit requests, reducing the required wait states
 - Key-protected program, erase and lock/unlock sequencer
 - Single command for erasing, programming and locking operations
 - Interrupt generation in case of forbidden operation

7.4 External Bus Interface

- Integrates Three External Memory Controllers:
 - Static Memory Controller
 - SDRAM Controller
 - ECC Controller
- Additional Logic for NAND Flash and CompactFlash® Support
 - NAND Flash support: 8-bit as well as 16-bit devices are supported
 - CompactFlash support: all modes (Attribute Memory, Common Memory, I/O, True IDE) are supported but the signals _IOIS16 (I/O and True IDE modes) and -ATA SEL (True IDE mode) are not handled.
- Optimized External Bus:
 - 16- or 32-bit Data Bus (32-bit Data Bus for SDRAM only)
 - Up to 23-bit Address Bus, Up to 8-Mbytes Addressable
 - Up to 8 Chip Selects, each reserved to one of the eight Memory Areas
 - Optimized pin multiplexing to reduce latencies on External Memories
- Configurable Chip Select Assignment:
 - Static Memory Controller on NCS0
 - SDRAM Controller or Static Memory Controller on NCS1
 - Static Memory Controller on NCS2, Optional CompactFlash Support
 - Static Memory Controller on NCS3, NCS5 - NCS6, Optional NAND Flash Support
 - Static Memory Controller on NCS4, Optional CompactFlash Support
 - Static Memory Controller on NCS7

7.5 Static Memory Controller

- External memory mapping, 512-Mbyte address space
- 8-, or 16-bit Data Bus
- Up to 8 Chip Select Lines
- Multiple Access Modes supported
 - Byte Write or Byte Select Lines
 - Two different Read Protocols for each Memory Bank

8. Memories

- 512 Kbytes of Flash Memory (SAM7SE512)
 - dual plane
 - two contiguous banks of 1024 pages of 256 bytes
 - Fast access time, 30 MHz single-cycle access in Worst Case conditions
 - Page programming time: 6 ms, including page auto-erase
 - Page programming without auto-erase: 3 ms
 - Full chip erase time: 15 ms
 - 10,000 write cycles, 10-year data retention capability
 - 32 lock bits, each protecting 32 lock regions of 64 pages
 - Protection Mode to secure contents of the Flash
- 256 Kbytes of Flash Memory (SAM7SE256)
 - single plane
 - one bank of 1024 pages of 256 bytes
 - Fast access time, 30 MHz single-cycle access in Worst Case conditions
 - Page programming time: 6 ms, including page auto-erase
 - Page programming without auto-erase: 3 ms
 - Full chip erase time: 15 ms
 - 10,000 cycles, 10-year data retention capability
 - 16 lock bits, each protecting 16 lock regions of 64 pages
 - Protection Mode to secure contents of the Flash
- 32 Kbytes of Flash Memory (SAM7SE32)
 - single plane
 - one bank of 256 pages of 128 bytes
 - Fast access time, 30 MHz single-cycle access in Worst Case conditions
 - Page programming time: 6 ms, including page auto-erase
 - Page programming without auto-erase: 3 ms
 - Full chip erase time: 15 ms
 - 10,000 cycles, 10-year data retention capability
 - 8 lock bits, each protecting 8 lock regions of 32 pages
 - Protection Mode to secure contents of the Flash
- 32 Kbytes of Fast SRAM (SAM7SE512/256)
 - Single-cycle access at full speed
- 8 Kbytes of Fast SRAM (SAM7SE32)
 - Single-cycle access at full speed

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

8.1.2.2 *Embedded Flash Controller*

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit Prefetch Buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

- Two EFCs (EFC0 and EFC1) are embedded in the SAM7SE512 to control each plane of 256 KBytes. Dual plane organization allows concurrent Read and Program.
- One EFC (EFC0) is embedded in the SAM7SE256 to control the single plane 256 KBytes.
- One EFC (EFC0) is embedded in the SAM7SE32 to control the single plane 32 KBytes.

8.1.2.3 *Lock Regions*

The SAM7SE512 Embedded Flash Controller manages 32 lock bits to protect 32 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE512 contains 32 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

The SAM7SE256 Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE256 contains 16 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

The SAM7SE32 Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE32 contains 8 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the EFC triggers an interrupt.

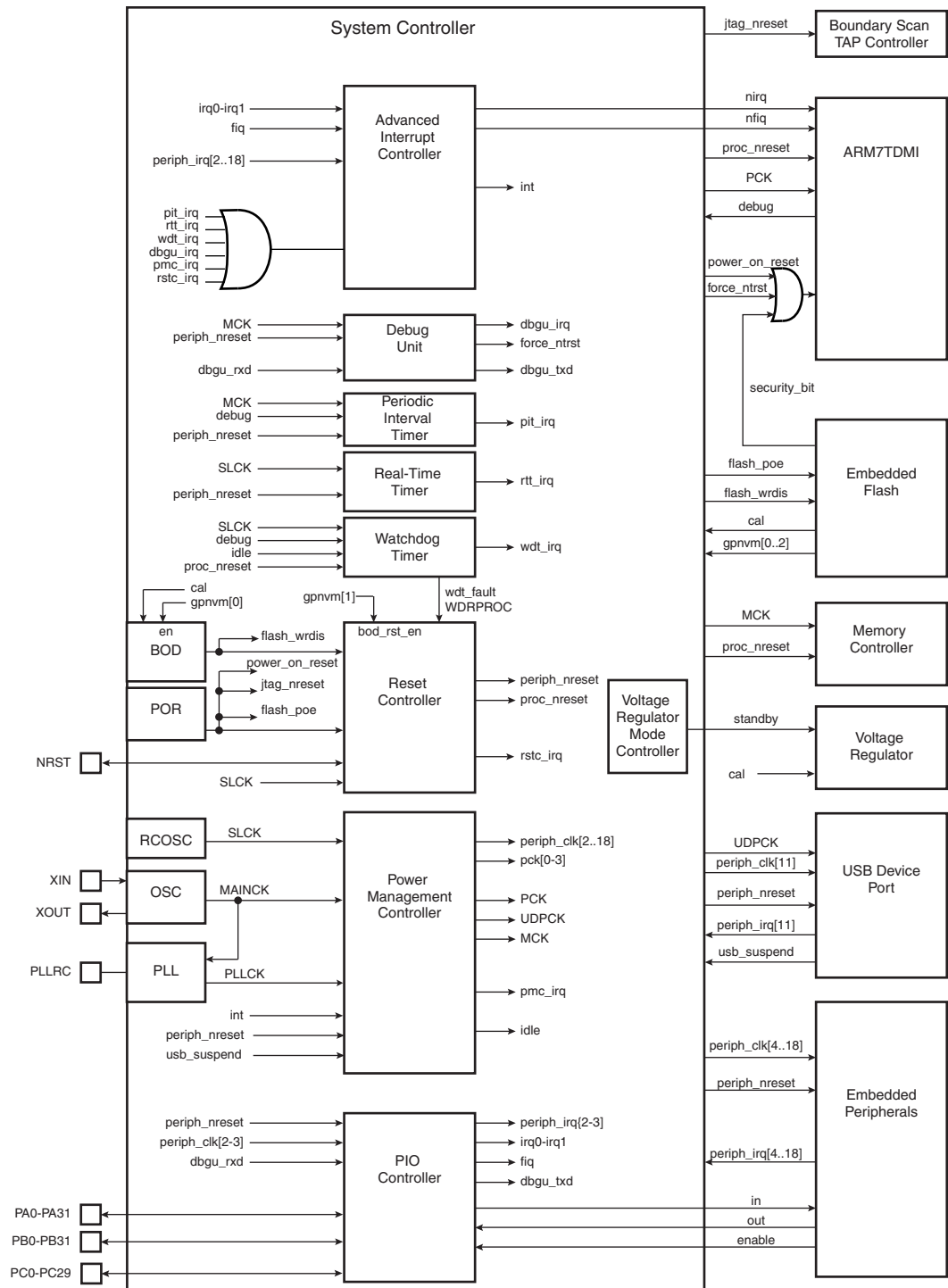
The 32 (SAM7SE512), 16 (SAM7SE256) or 8 (SAM7SE32) NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.1.2.4 *Security Bit Feature*

The SAM7SE512/256/32 features a security bit, based on a specific NVM-bit. When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden.

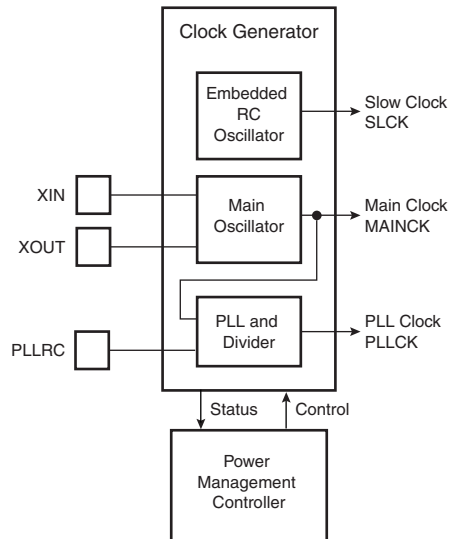
Figure 9-1. System Controller Block Diagram



- Main Oscillator frequency ranges between 3 and 20 MHz
- Main Oscillator can be bypassed
- PLL output ranges between 80 and 220 MHz

It provides SLCK, MAINCK and PLLCK.

Figure 9-2. Clock Generator Block Diagram



9.3 Power Management Controller

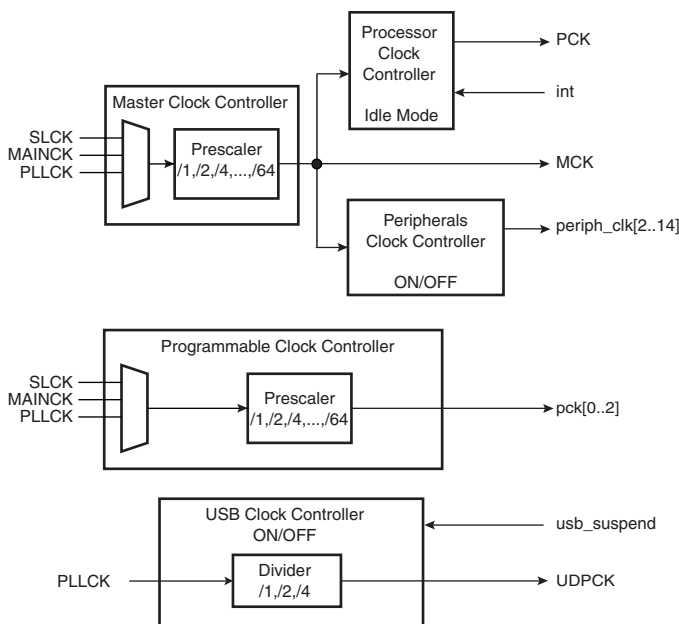
The Power Management Controller uses the Clock Generator outputs to provide:

- the Processor Clock PCK
- the Master Clock MCK
- the USB Clock UDPCCK
- all the peripheral clocks, independently controllable
- three programmable clock outputs

The Master Clock (MCK) is programmable from a few hundred Hz to the maximum operating frequency of the device.

The Processor Clock (PCK) switches off when entering processor idle mode, thus allowing reduced power consumption while waiting for an interrupt.

Figure 9-3. Power Management Controller Block Diagram



9.4 Advanced Interrupt Controller

- Controls the interrupt lines (nIRQ and nFIQ) of an ARM Processor
- Individually maskable and vectored interrupt sources
 - Source 0 is reserved for the Fast Interrupt Input (FIQ)
 - Source 1 is reserved for system peripherals (RTT, PIT, EFC, PMC, DBGU, etc.)
 - Other sources control the peripheral interrupts or external interrupts
 - Programmable edge-triggered or level-sensitive internal sources
 - Programmable positive/negative edge-triggered or high/low level-sensitive external sources
- 8-level Priority Controller
 - Drives the normal interrupt nIRQ of the processor
 - Handles priority of the interrupt sources
 - Higher priority interrupts can be served during service of lower priority interrupt
- Vectoring
 - Optimizes interrupt service routine branch and execution
 - One 32-bit vector register per interrupt source
 - Interrupt vector register reads the corresponding current interrupt vector
- Protect Mode
 - Easy debugging by preventing automatic operations
- Fast Forcing
 - Permits redirecting any interrupt source on the fast interrupt
- General Interrupt Mask
 - Provides processor synchronization on events without triggering an interrupt

10. Peripherals

10.1 User Interface

The User Peripherals are mapped in the 256 MBytes of the address space between 0xF000 0000 and 0xFFFF EFFF. Each peripheral is allocated 16 Kbytes of address space.

A complete memory map is presented in [Figure 8-1 on page 22](#).

10.2 Peripheral Identifiers

The SAM7SE512/256/32 embeds a wide range of peripherals. [Table 10-1](#) defines the Peripheral Identifiers of the SAM7SE512/256/32. Unique peripheral identifiers are defined for both the Advanced Interrupt Controller and the Power Management Controller.

Table 10-1. Peripheral Identifiers

Peripheral ID	Peripheral Mnemonic	Peripheral Name	External Interrupt
0	AIC	Advanced Interrupt Controller	FIQ
1	SYSC ⁽¹⁾		
2	PIOA	Parallel I/O Controller A	
3	PIOB	Parallel I/O Controller B	
4	PIOC	Parallel I/O Controller C	
5	SPI	Serial Peripheral Interface 0	
6	US0	USART 0	
7	US1	USART 1	
8	SSC	Synchronous Serial Controller	
9	TWI	Two-wire Interface	
10	PWMC	PWM Controller	
11	UDP	USB Device Port	
12	TC0	Timer/Counter 0	
13	TC1	Timer/Counter 1	
14	TC2	Timer/Counter 2	
15	ADC ⁽¹⁾	Analog-to Digital Converter	
16-28	reserved		
29	AIC	Advanced Interrupt Controller	IRQ0
30	AIC	Advanced Interrupt Controller	IRQ1

Note: 1. Setting SYSC and ADC bits in the clock set/clear registers of the PMC has no effect. The System Controller is continuously clocked. The ADC clock is automatically started for the first conversion. In Sleep Mode the ADC clock is automatically stopped after each conversion.

10.5 PIO Controller B Multiplexing

Table 10-3. Multiplexing on PIO Controller B

PIO Controller B				Application Usage	
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments
PB0	TIOA0	A0/NBS0			
PB1	TIOB0	A1/NBS2			
PB2	SCK0	A2			
PB3	NPCS3	A3			
PB4	TCLK0	A4			
PB5	NPCS3	A5			
PB6	PCK0	A6			
PB7	PWM3	A7			
PB8	ADTRG	A8			
PB9	NPCS1	A9			
PB10	NPCS2	A10			
PB11	PWM0	A11			
PB12	PWM1	A12			
PB13	PWM2	A13			
PB14	PWM3	A14			
PB15	TIOA1	A15			
PB16	TIOB1	A16/BA0			
PB17	PCK1	A17/BA1			
PB18	PCK2	D16			
PB19	FIQ	D17			
PB20	IRQ0	D18			
PB21	PCK1	D19			
PB22	NPCS3	D20			
PB23	PWM0	D21			
PB24	PWM1	D22			
PB25	PWM2	D23			
PB26	TIOA2	D24			
PB27	TIOB2	D25			
PB28	TCLK1	D26			
PB29	TCLK2	D27			
PB30	NPCS2	D28			
PB31	PCK2	D29			

10.6 PIO Controller C Multiplexing

Multiplexing on PIO Controller C

PIO Controller C				Application Usage	
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments
PC0	D0				
PC1	D1				
PC2	D2				
PC3	D3				
PC4	D4				
PC5	D5				
PC6	D6				
PC7	D7				
PC8	D8	RTS1			
PC9	D9	DTR1			
PC10	D10	PCK0			
PC11	D11	PCK1			
PC12	D12	PCK2			
PC13	D13				
PC14	D14	NPCS1			
PC15	D15	NCS3/NANDCS			
PC16	A18	NWAIT			
PC17	A19	NANDOE			
PC18	A20	NANDWE			
PC19	A21/NANDALE				
PC20	A22/REG/NANDCLE	NCS7			
PC21		NWR0/NWE/CFWE			
PC22		NRD/CFOE			
PC23	CFRNW	NCS0			

10.7 Serial Peripheral Interface

- Supports communication with external serial devices
 - Four chip selects with external decoder allow communication with up to 15 peripherals
 - Serial memories, such as DataFlash® and 3-wire EEPROMs
 - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
 - External co-processors
- Master or slave serial peripheral bus interface

- 8- to 16-bit programmable data length per chip select
- Programmable phase and polarity per chip select
- Programmable transfer delays per chip select, between consecutive transfers and between clock and data
- Programmable delay between consecutive transfers
- Selectable mode fault detection
- Maximum frequency at up to Master Clock

10.8 Two Wire Interface

- Master, Multi-Master and Slave Mode Operation
- Compatibility with standard two-wire serial memories
- One, two or three bytes for slave address
- Sequential read/write operations
- Bit Rate: Up to 400 Kbit/s
- General Call Supported in Slave Mode

10.9 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
 - 1, 1.5 or 2 stop bits in Asynchronous Mode
 - 1 or 2 stop bits in Synchronous Mode
 - Parity generation and error detection
 - Framing error detection, overrun error detection
 - MSB or LSB first
 - Optional break generation and detection
 - By 8 or by 16 over-sampling receiver frequency
 - Hardware handshaking RTS - CTS
 - Modem Signals Management DTR-DSR-DCD-RI on USART1
 - Receiver time-out and transmitter timeguard
 - Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards
 - NACK handling, error counter with repetition and iteration limit
- IrDA[®] modulation and demodulation
 - Communication at up to 115.2 Kbps
- Test Modes
 - Remote Loopback, Local Loopback, Automatic Echo

10.10 Serial Synchronous Controller

- Provides serial synchronous communication links used in audio and telecom applications
- Contains an independent receiver and transmitter and a common clock divider

- Offers a configurable frame sync and data length
- Receiver and transmitter can be programmed to start automatically or on detection of different event on the frame sync signal
- Receiver and transmitter include a data signal, a clock signal and a frame synchronization signal

10.11 Timer Counter

- Three 16-bit Timer Counter Channels
 - Two output compare or one input capture per channel
- Wide range of functions including:
 - Frequency measurement
 - Event counting
 - Interval measurement
 - Pulse generation
 - Delay timing
 - Pulse Width Modulation
 - Up/down capabilities
- Each channel is user-configurable and contains:
 - Three external clock inputs
 - Five internal clock inputs, as defined in [Table 10-4](#)

Table 10-4. Timer Counter Clocks Assignment

TC Clock input	Clock
TIMER_CLOCK1	MCK/2
TIMER_CLOCK2	MCK/8
TIMER_CLOCK3	MCK/32
TIMER_CLOCK4	MCK/128
TIMER_CLOCK5	MCK/1024

- Two multi-purpose input/output signals
- Two global registers that act on all three TC channels

10.12 PWM Controller

- Four channels, one 16-bit counter per channel
- Common clock generator, providing thirteen different clocks
 - One Modulo n counter providing eleven clocks
 - Two independent linear dividers working on modulo n counter outputs
- Independent channel programming
 - Independent enable/disable commands
 - Independent clock selection
 - Independent period and duty cycle, with double buffering
 - Programmable selection of the output waveform polarity
 - Programmable center or left aligned output waveform

10.13 USB Device Port

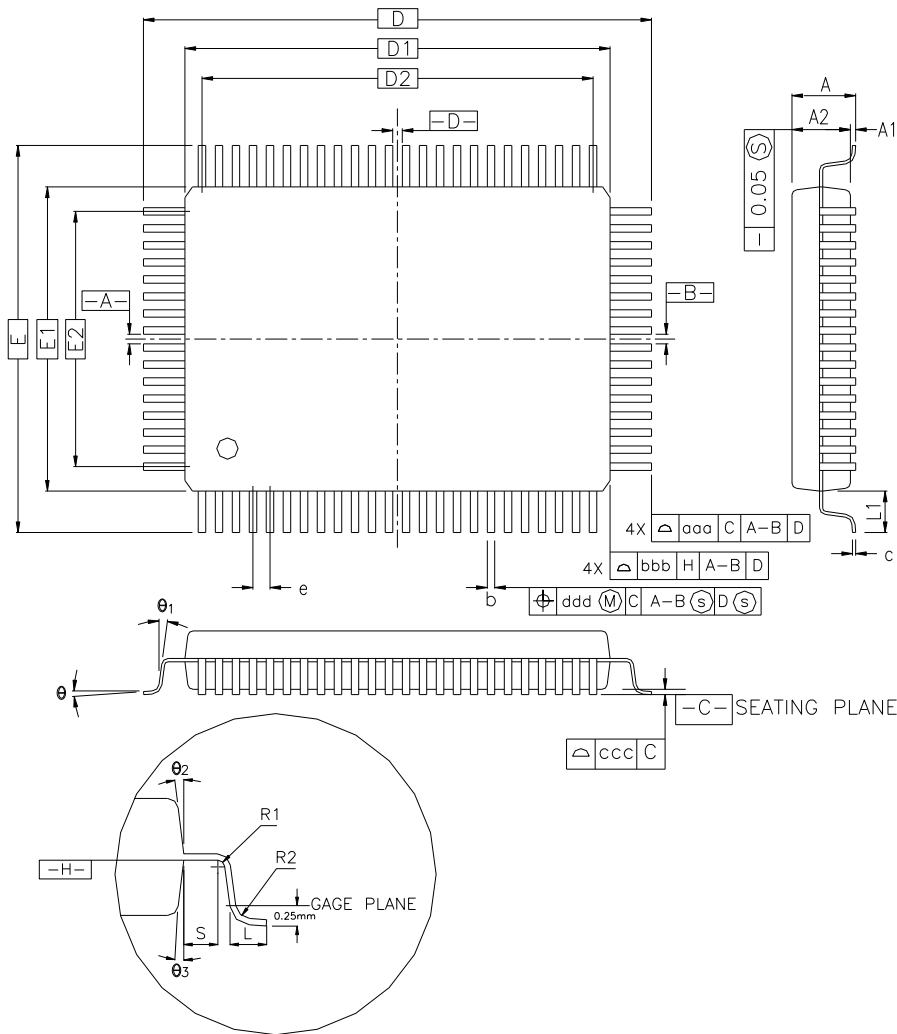
- USB V2.0 full-speed compliant, 12 Mbits per second.
- Embedded USB V2.0 full-speed transceiver
- Embedded 2688-byte dual-port RAM for endpoints
- Eight endpoints
 - Endpoint 0: 64bytes
 - Endpoint 1 and 2: 64 bytes ping-pong
 - Endpoint 3: 64 bytes
 - Endpoint 4 and 5: 512 bytes ping-pong
 - Endpoint 6 and 7: 64 bytes ping-pong
 - Ping-pong Mode (two memory banks) for Isochronous and bulk endpoints
- Suspend/resume logic
- Integrated Pull-up on DDP

10.14 Analog-to-Digital Converter

- 8-channel ADC
- 10-bit 384 Ksamples/sec. or 8-bit 583 Ksamples/sec. Successive Approximation Register ADC
- ± 2 LSB Integral Non Linearity, ± 1 LSB Differential Non Linearity
- Integrated 8-to-1 multiplexer, offering eight independent 3.3V analog inputs
- External voltage reference for better accuracy on low voltage inputs
- Individual enable and disable of each channel
- Multiple trigger sources
 - Hardware or software trigger
 - External trigger pin
 - Timer Counter 0 to 2 outputs TIOA0 to TIOA2 trigger
- Sleep Mode and conversion sequencer
 - Automatic wakeup on trigger and back to sleep mode after conversions of all enabled channels
- Each analog input shared with digital signals

11. Package Drawings

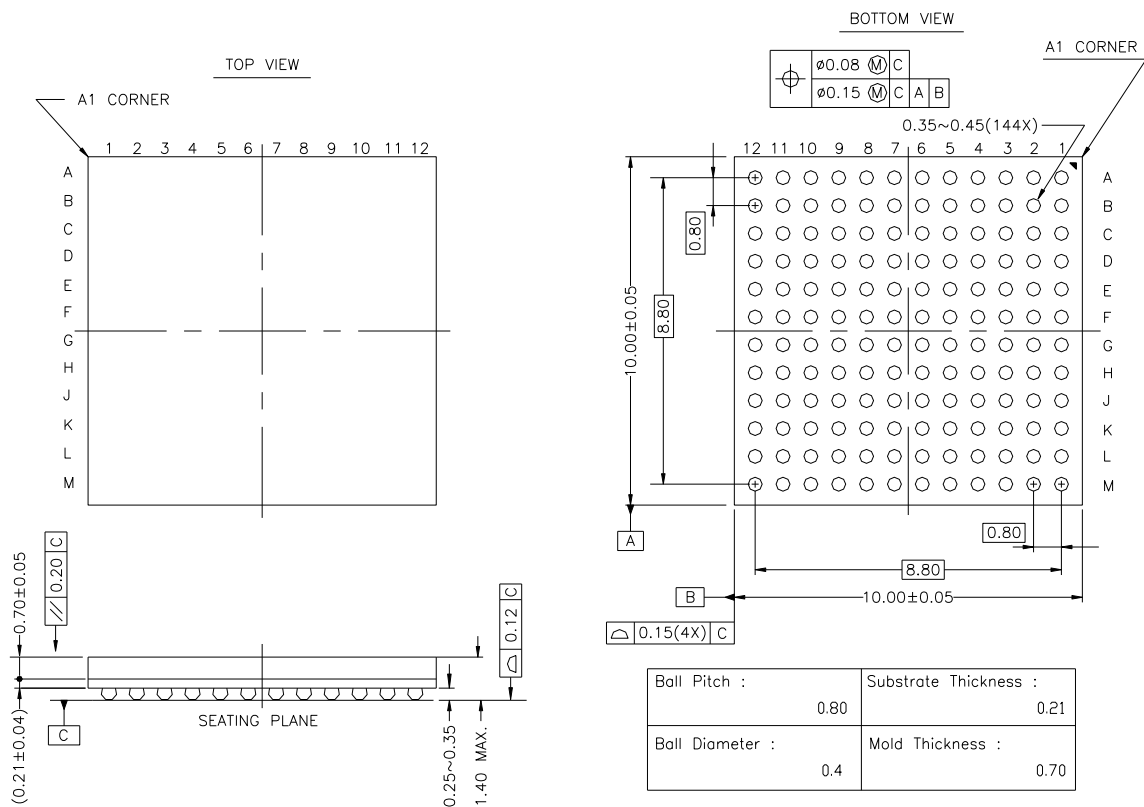
Figure 11-1. 128-lead LQFP Package Drawing



CONTROL DIMENSIONS ARE IN MILLIMETERS.

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	—	1.60	—	—	0.063
A1	0.05	—	0.15	0.002	—	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	22.00 BSC.			0.866 BSC.		
D1	20.00 BSC.			0.787 BSC.		
E	16.00 BSC.			0.630 BSC.		
E1	14.00 BSC.			0.551 BSC.		
R2	0.08	—	0.20	0.003	—	0.008
R1	0.08	—	—	0.003	—	—
θ	0°	3.5°	7°	0°	3.5°	7°
θ ₁	0°	—	—	0°	—	—
θ ₂	11°	12°	13°	11°	12°	13°
θ ₃	11°	12°	13°	11°	12°	13°
c	0.09	—	0.20	0.004	—	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L ₁	1.00 REF			0.039 REF		
S	0.20	—	—	0.008	—	—
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	18.50			0.728		
E2	12.50			0.492		
TOLERANCES OF FORM AND POSITION						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Figure 11-2. 144-ball LFBGA Package Drawing



All dimensions are in mm

Revision History

Doc. Rev	Comments	Change Request Ref.
	First issue	
6222AS	Revised Memories with condensed mapping. Added Package Outlines and 144-ball LFBGA pin and ordering information.	#2709
6222BS	Section 12. "Ordering Information" on page 45 ordering information code reference changed	#3699
6222CS	Section 6.1 "JTAG Port Pins" , Section 6.3 "Reset Pin" , Section 6.5 "SDCK Pin" , removed statement: "not 5V tolerant" Section 7.6 "SDRAM Controller" , Mobile SDRAM controller added to SDRAMC features INL and DNL updated in Section 10.14 "Analog-to-Digital Converter" "Features" on page 2, Fully Static Operation; added, up to 55 MHz at 1.8V and 85°C worst case conditions Section 7.1 "ARM7TDMI Processor" , Runs at up to 55 MHz, providing 0.9 MIPS/MHz (core supplied with 1.8V) Section 7.8 "Peripheral DMA Controller" PDC priority list added Section 7.5 "Static Memory Controller" , Multiple device adaptability includes: compliant w/PSRAM in synchronous operations.	#3826 #4005 #3924 #3833 review
6222DS	Figure 8-1 "SAM7SE Memory Mapping" Compact Flash not shown w/EBI Chip Select 5. Compact Flash is shown with EBI Chip Select 2. Section 8.1.2.1 "Flash Overview" , updated AT91SAM7SE32 ..."reads as 8192 32-bit words." Section 6. "I/O Lines Considerations" , "JTAG Port Pins" , "Test Pin" , "Reset Pin" , "ERASE Pin" descriptions updated	4804 4512 5062
6222ES	Section 10.11 "Timer Counter" ,the TC has two output compare and one input capture per channel.	4209
6222FS	Features: "Mode for General Purpose Two-wire UART Serial Communication" added to "Debug Unit (DBGU)" . Signal Description: Table 3-1, "Signal Description List" , AD0-AD3 and AD4-AD7 comments reversed. System Controller: Figure 9-1 "System Controller Block Diagram" , 'periph_nreset' changed into 'power_on_reset' for RTT.	5846 5271 5222
6222GS	MRL B Ordering Codes added to Table 12-1, "Ordering Information" 'Product Description' changed to 'AT91SAM ARM-based Flash MCU' on the first page. 'AT91SAM' product prefix changed to 'SAM', except for Chip ID and ordering codes.	7749 rfo